





DMN4036LK3

**40V N-CHANNEL ENHANCEMENT MODE MOSFET** 

#### Product Summary

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub> T <sub>A</sub> = 25°C		
40V	36mΩ @ V <sub>GS</sub> = 10V	12.2A		
	61mΩ @ V <sub>GS</sub> = 4.5V	9.4A		

### **Description and Applications**

This new generation MOSFET has been designed to minimize the onstate resistance (R<sub>DS(on)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- DC-DC Converters
- Power management functions

#### **Features and Benefits**

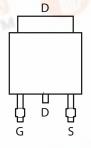
- Low on-resistance
- Fast switching speed
- "Green" component and RoHS compliant (Note 1)

#### **Mechanical Data**

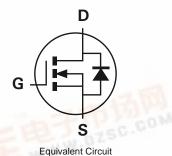
- Case: TO252-3L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Below
- Ordering Information: See Below
- Weight: 0.33 grams (approximate)



TOP VIEW



PIN OUT -TOP VIEW



#### Ordering Information (Note 1)

Product Marking		Reel size (inches)	Tape width (mm)	Quantity per reel	
DMN4036LK3-13	N4036L	13	16	2,500	

Note: 1. Diodes, Inc. defines "Green" products as those which are Eu RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

### **Marking Information**

N4036LK3

Document Revision: 1



>:! = Manufacturer's Marking N4036L = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 09 = 2009) WW = Week (01-52)





### Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Cha	aracteristic		Symbol	Value	Unit	
Drain-Source voltage			V <sub>DSS</sub> 40		V	
Gate-Source voltage			V <sub>GS</sub>	±20	V	
		(Note 3)	I <sub>D</sub>	12.2		
Continuous Drain current	$V_{GS} = 10V$	T <sub>A</sub> =70°C (Note 3)		9.7	А	
		(Note 2)		8.5		
Pulsed Drain current	V <sub>GS</sub> = 10V	(Note 4)	IDM	31.7	А	
Continuous Source current (Body diode) (Note 3)		IS	10.4	A		
Pulsed Source current (Body diode) (Note 4)		I <sub>SM</sub>	31.7	А		

#### Thermal Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit		
	(Note 2)		4.12 33		
Power dissipation Linear derating factor	(Note 3)	PD	8.49 W 67.9 mW/ <sup>c</sup>		
	(Note 5)		2.12 16.9		
Thermal Resistance, Junction to Ambient	(Note 2) (Note 3) (Note 5)	R <sub>0JA</sub>	30.3 14.7 59.0	°C/W	
Thermal Resistance, Junction to Lead	(Note 6)	R <sub>θJL</sub>	3.1	1	
Operating and storage temperature range		TJ, TSTG	-55 to 150	°C	

2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is Notes: measured when operating in a steady-state condition.

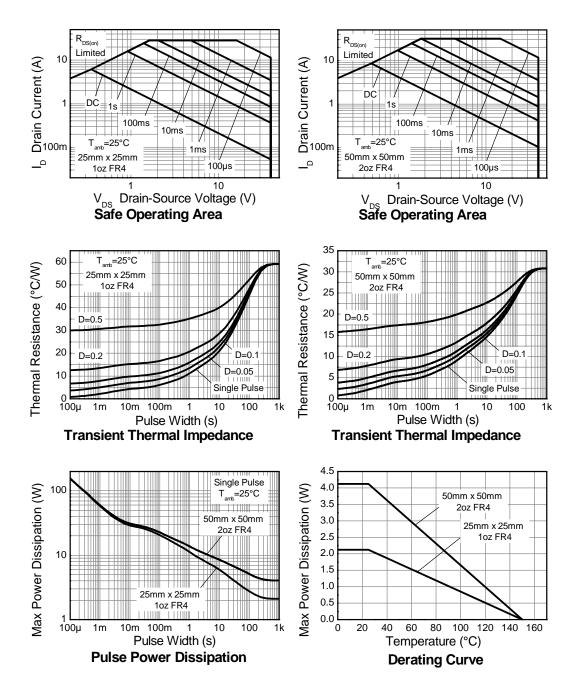
3. Same as note 2, except the device is measured at t  $\leq$  10 sec. 4. Same as note 2, except the device is pulsed with D = 0.02 and pulse width 300 µs. The pulse current is limited by the maximum junction temperature. 5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

6. Thermal resistance from junction to solder-point (at the end of the drain lead).





#### **Thermal Characteristics**







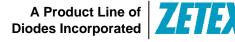
# Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test	Condition	
OFF CHARACTERISTICS						•		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	40		_	V	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_		0.5	μA	$V_{DS}$ = 40V, $V_{GS}$	= 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_		±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V		
ON CHARACTERISTICS								
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0		3.0	V	$I_{D}$ = 250µA, V <sub>DS</sub>	s= V <sub>GS</sub>	
Static Drain-Source On-Resistance (Note 7)	р			0.036	Ω	$V_{GS}$ = 10V, $I_{D}$ =	12A	
Static Drain-Source On-Resistance (Note 7)	R <sub>DS (ON)</sub>	_		0.061	12	V <sub>GS</sub> = 4.5V, I <sub>D</sub> =	6A	
Forward Transconductance (Notes 7 & 8)	<b>g</b> fs	_	19.6		S	V <sub>DS</sub> = 15V, I <sub>D</sub> = 12A		
Diode Forward Voltage (Note 7)	V <sub>SD</sub>	_	0.96	1.1	V	I <sub>S</sub> = 12A, V <sub>GS</sub> = 0V		
Reverse recovery time (Note 8)	t <sub>rr</sub>		112	—	ns	-I <sub>S</sub> = 12A, di/dt= 100A/μs		
Reverse recovery charge (Note 8)	Q <sub>rr</sub>	_	926	—	nC			
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance	C <sub>iss</sub>	_	453		pF			
Output Capacitance	C <sub>oss</sub>	_	79.1		pF	−V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V −f= 1MHz		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	40.5	_	pF			
Total Gate Charge	Qg	_	4.9	_	nC	V <sub>GS</sub> = 4.5V		
Total Gate Charge	Qg	_	9.2	_	nC		V <sub>DS</sub> = 20V	
Gate-Source Charge	Q <sub>gs</sub>	_	1.7		nC	V <sub>GS</sub> = 10V	I <sub>D</sub> = 12A	
Gate-Drain Charge	Q <sub>gd</sub>	_	2.7		nC			
Turn-On Delay Time (Note 9)	t <sub>D(on)</sub>	_	3.2		ns		·	
Turn-On Rise Time (Note 9)	tr	_	11.7		ns	V <sub>DD</sub> = 20V, V <sub>GS</sub> = 10V		
Turn-Off Delay Time (Note 9)	t <sub>D(off)</sub>	_	11.6	_	ns	I <sub>D</sub> = 12A, R <sub>G</sub> ≅ 6.0Ω		
Turn-Off Fall Time (Note 9)	tf	_	9.5	_	ns	7		

Notes:

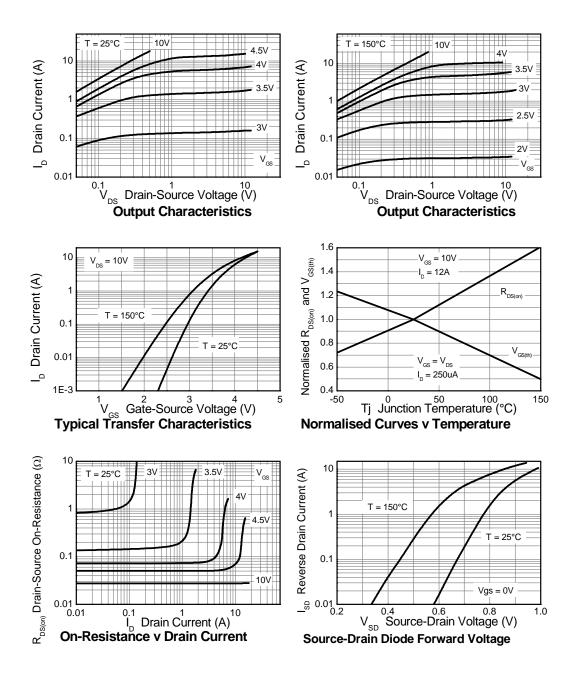
Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
For design aid only, not subject to production testing.
Switching characteristics are independent of operating junction temperatures.





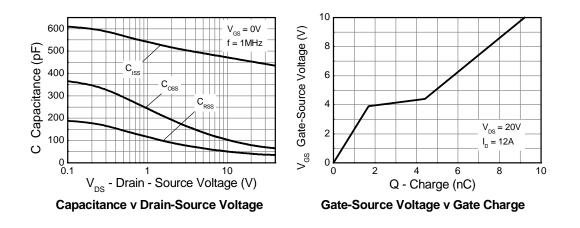


# **Typical Characteristics**

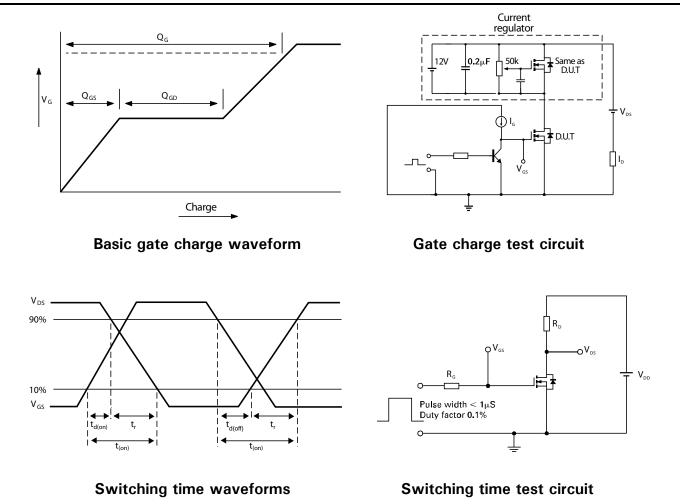




## **Typical Characteristics - continued**

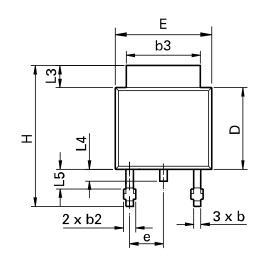


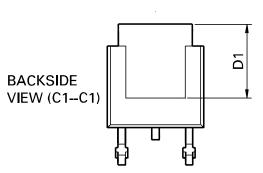
**Test Circuits** 

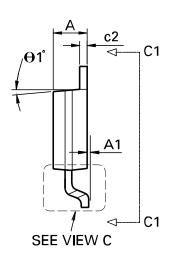


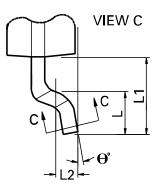


# Package Outline Dimensions







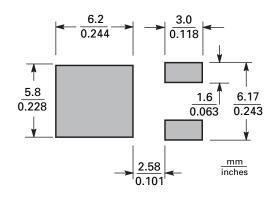


DIM	Inc	hes	Millin	neters	DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
А	0.086	0.094	2.18	2.39	е	0.090 BSC		2.29 BSC	
A1	-	0.005	-	0.127	н	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
с	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	θ1°	0°	10°	0°	10°
Е	0.250	0.265	6.35	6.73	θ°	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-



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#### Suggested Pad Layout



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